DATA SHEET

Part No.	AN13300A
Package Code No.	*SOP022 - P - 0375C

SEMICONDUCTOR COMPANY MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

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AN13300A Silicon Monolithic Bipolar IC

Features

• Video signal input - output interface for DSP

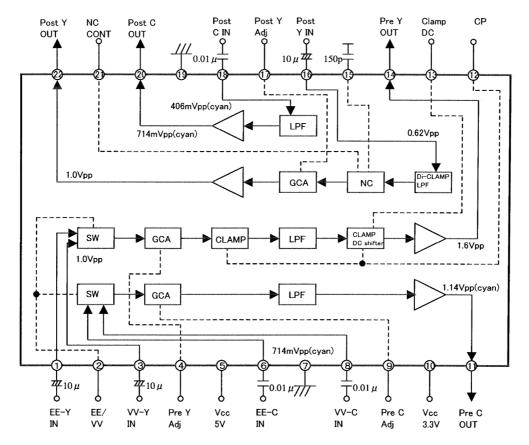
Applications

• VCR (Digital Video equipment)

Package

• Dill - 22Pin plastic package SO Type

Block Diagram



■Pin Descriptions

Pin No.	Function	Impedance	Pin No.	Function	Impedance
1	EE - Y IN	30k	12	Clamp Pulse IN	210k
2	EE / VV SW	210k	13	Clamp DC	65k
3	VV - Y IN	30k	14	Pre - Y OUT	E. F.
4	Pre - Y Adj.	64k	15	N. C. Capacitor	500k
5	V _{CC1} (5V)		16	Post - Y IN	26k
6	EE - C IN	30k	17	Post - Y Adj.	65k
7	GND		18	Post - C IN	21k
8	VV - C IN	10k	19	GND	
9	Pre - C Adj.	62k	20	Post - C OUT	E. F.
10	V _{CC2} (3.3 V)		21	N. C. Control	65k
11	Pre - C OUT	E. F.	22	Post - Y OUT	E. F.

AN13300A

Panasonic

■ Absolute Maximum Ratings

No.	Parameter	Symbol	Rating		Unit	Note
1	Storage temperature	T _{stg}	-55 to +125		°C	*
2	Operating ambient temperature	T _{opr} -20 to +70		-20 to +70	°C	*
3	Operating ambient atmospheric pressure	P_{opr} 1.013 × 10 ⁵ ± 0.61 × 10 ⁵		Pa		
4	Operating constant gravity	G _{opr}	9 810		m/S ²	
5	Operating shock	S _{opr}	4 900		m/S ²	
6	Sumply voltage	V _{CC}	V _{CC1}	5.5	- V	
6	Supply voltage		V _{CC2}	3.6		
7	7 Supply current	I _{CC}	I _{CC1}	35	mA	
			I _{CC2}	0.5		
8	Power dissipation	P _D	195		W	

Note) *: Expect for the operating ambient temperature and storage temperature , all ratings are for $Ta = 25^{\circ}C$.

Operating Supply Voltage Range

Operating supply voltage range	V _{CC1}	4.75 V to 5.25 V
	V _{CC2}	3.1 V to 3.5 V

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